

## Minutes from OPEN INNOVATION WP 3 technical meeting

19-12-2016 14.00 to 15.30

Attendance: Longfei (TU/e), Weiming (TU/e), Kevin (TU/e), Pim (Technobis), Roel (Smart), Rui (Smart), Luc (Smart), Ronald (Bright)

### WP 3.1 BB Design

- Focus on design of MQW stack for modulator in next phase.
- SP20 will include growth of that stack in a separate wafer.
- Initial testing of new MQW stack will use passive wafer (single growth, 3x different stacks).
- Detailed RF line specification is the focus of next period. This will act as an interface to Smart photonics
- Adoption of SSC design from WIPE project into MPW runs is decided.
- DBR + DFB specifications for technology will be the focus of next period.
- **[Action, Bright]** Design different gratings for SP20 (chirped, sampled, etc)
- Available data for grating experiments will be gathered from Zhao Dan.
- **[Action, TU/e]** contact Lionix (Arne) and propose InP/Triplex chip activity in openPICs or ask what they would like to have as activity in openPICs.

### WP 3.3 BB Characterization

- Presented structures for SP 19: reliability and performance of plated metal
- Bright designs AWG as test structure for BB test cell in SP 20.

### WP 3.2 PDK Content

### WP 3.4 Design Environment

- Discussion on design workflow as of now and some of the major problems. Critical points include mask assembly and BB replacement steps that are performed in Phoenix code and prone to errors. Examples were mentioned that involved exchange of custom building blocks between designers which led to disappearance of those in the final GDS file. A clearer documentation and re-organization of the workflow is desired.
- Propose to Phoenix software to address this issue and develop solution focused on GDS level manipulation.